TOSHIBA Multi-Chip Device Silicon P-Channel MOS Type (U-MOS II) + N-Channel MOS Type (Planer)

## SSM6E01TU

#### Load Switch Applications

- P-channel MOSFET and N-channel MOSFET incorporated into one package.
- Low power dissipation due to P-channel MOSFET that features low RDS (ON) and low-voltage operation

### Q1 Absolute Maximum Ratings (Ta = 25°C)

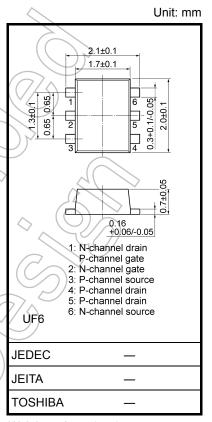
Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		$V_{DS}$	-12	V (	
Gate-Source voltage		$V_{GSS}$	±12	M	
Drain current	DC	ΙD	-1.0	(A)	
	Pulse	I <sub>DP</sub> (Note 2)	-2.0	$(\langle \rangle  \rangle  )$	

## Q2 Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		$V_{DS}$	20	V	
Gate-Source voltage		V <sub>GSS</sub>	10	V	
Drain current	DC	I <sub>D</sub> <	0.05		
	Pulse	I <sub>DP</sub> (Note 2)	0.2	∠ <sup>A</sup>	

# Absolute Maximum Ratings (Q1, Q2 common) (Ta = 25°C)

Characteristics	Symbol	Rating (	Unit
Drain power dissipation	P <sub>D</sub> (Note 1)	0.5	W/W
Channel temperature	Tch	150	√°C
Storage temperature range	T <sub>stg</sub>	-55 to 150	°C



Weight: 7.0 mg (typ.)

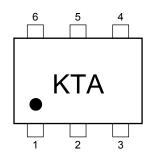
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

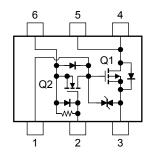
Note 1: Mounted on an FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu pad: 645 mm<sup>2</sup>)

Note 2: Pulse width limited by maximum channel temperature.

#### Marking



#### **Equivalent Circuit (top view)**



Start of commercial production 2002-10

#### **Handling Precaution**

This product has a MOS structure and is sensitive to electrostatic discharge. When handling individual devices (that have not yet been mounted on a PCB), ensure that the environment is protected against static electricity. Operators should wear anti-static clothing, containers and other objects which may come into direct contact with devices should be made of anti-static materials.

Thermal resistance  $R_{th\ (j-a)}$  and drain power dissipation  $P_D$  vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration.



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### Q1 Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 1.0 A, V <sub>GS</sub> = 0 V	_	_	1.2	V
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$	_	_	±1	μА
Drain-Source breakdown voltage	V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0$	-12	_	_	V
Drain cut-off current	I <sub>DSS</sub>	$V_{DS} = -12 \text{ V}, V_{GS} = 0$		_	-1	μА
Gate threshold voltage	V <sub>th</sub>	$V_{DS} = -3 \text{ V}, I_D = -0.1 \text{ mA}$	-0.4	) )	-1.1	V
Forward transfer admittance	Y <sub>fs</sub>	$V_{DS} = -3 \text{ V}, I_D = -0.5 \text{ A}$ (Note 3)	1.3	2.5	_	S
Drain-Source ON resistance	R <sub>DS</sub> (ON)	$I_D = -0.5 \text{ A}, V_{GS} = -4 \text{ V}$ (Note 3)	$\mathcal{C}$	125	160	mΩ
		$I_D = -0.5 \text{ A}, V_{GS} = -2.5 \text{ V}$ (Note 3)		180	240	
Input capacitance	C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	_	310	_	pF

Note 3: Pulse test

### **Q2 Electrical Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0$		<u> </u>	15	μА
Drain-Source breakdown voltage	V <sub>(BR)DSS</sub>	$I_D = 0.1 \text{ mA}, V_{GS} = 0$	_20	_		V
Drain cut-off current	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0$	) —	_	1	μΑ
Gate threshold voltage	V <sub>th</sub>	$V_{DS} = 3 \text{ V}, I_{D} = 0.1 \text{ mA}$	0.7	_	1.3	V
Forward transfer admittance	Y <sub>fs</sub>	$V_{DS} = 3 \text{ V}, I_{D} = 10 \text{ mA}$ (Note 3)	25	50		mS
Drain-Source ON resistance	R <sub>D</sub> \$ (ON)	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$ (Note 3)	_	4	10	Ω
Input capacitance	Ciss	V <sub>DS</sub> = 3 V, V <sub>GS</sub> = 0, f = 1 MHz	_	11	_	pF
Gate-Source resistance	RGS	V <sub>GS</sub> = 0 to 10 V	0.7	1.0	1.3	ΜΩ

Note 3: Pulse test

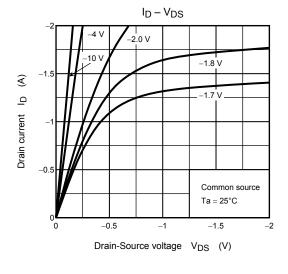
#### **Precaution**

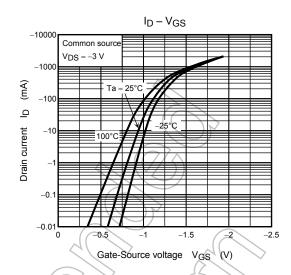
 $V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = \pm 100~\mu A$  for this product. For normal switching operation,  $V_{GS~(on)}$  requires higher voltage than  $V_{th}$  and  $V_{GS~(off)}$  requires lower voltage than  $V_{th}$ . (Relationship can be established as follows:  $V_{GS~(off)} < V_{th} < V_{GS~(on)}$ )

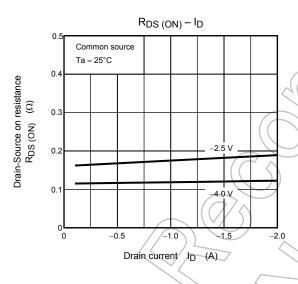
Please take this into consideration for using the device.

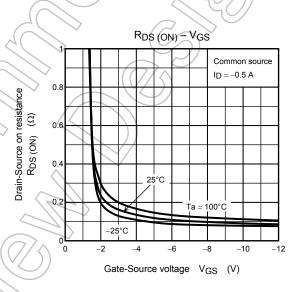
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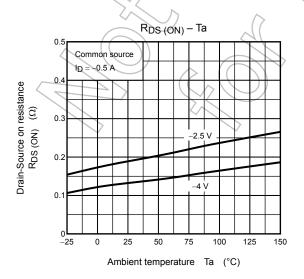
## Q1 (Pch MOSFET)

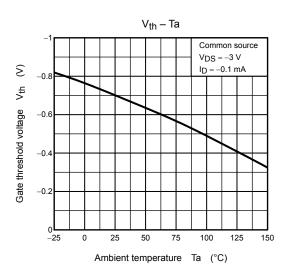




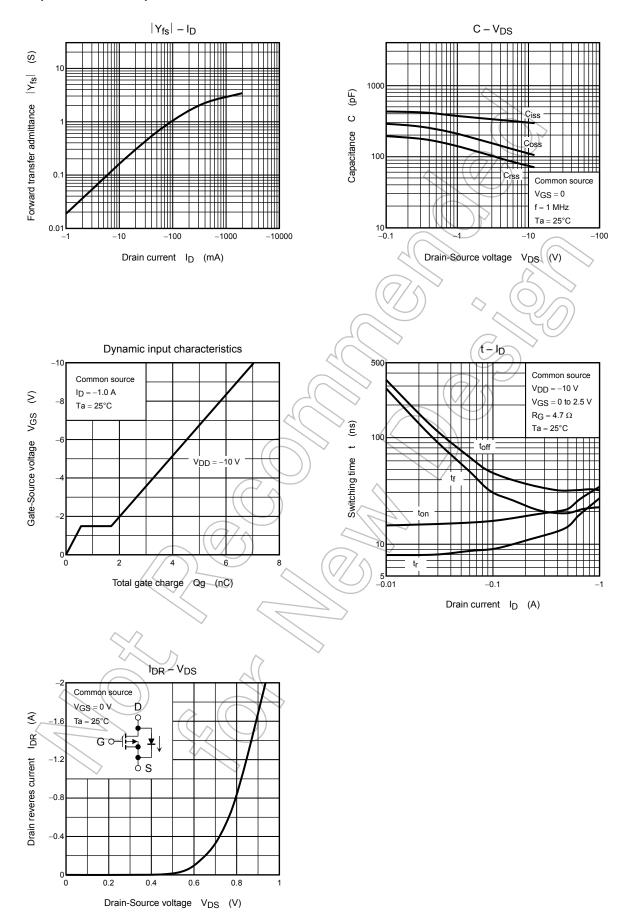






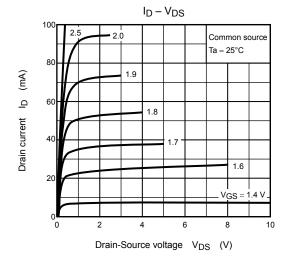


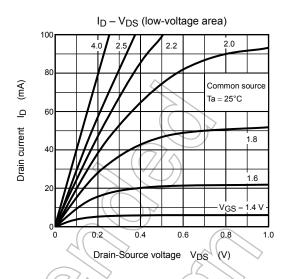
## Q1 (Pch MOSFET)

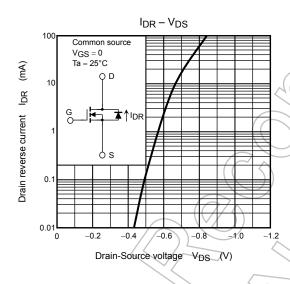


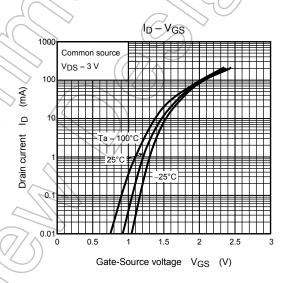
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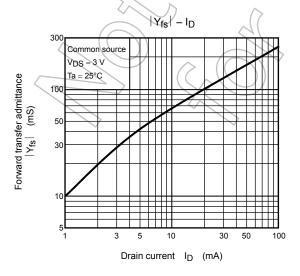
## Q2 (Nch MOSFET)

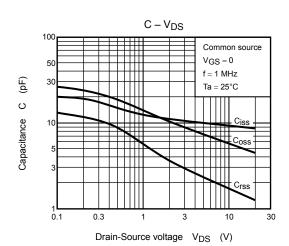




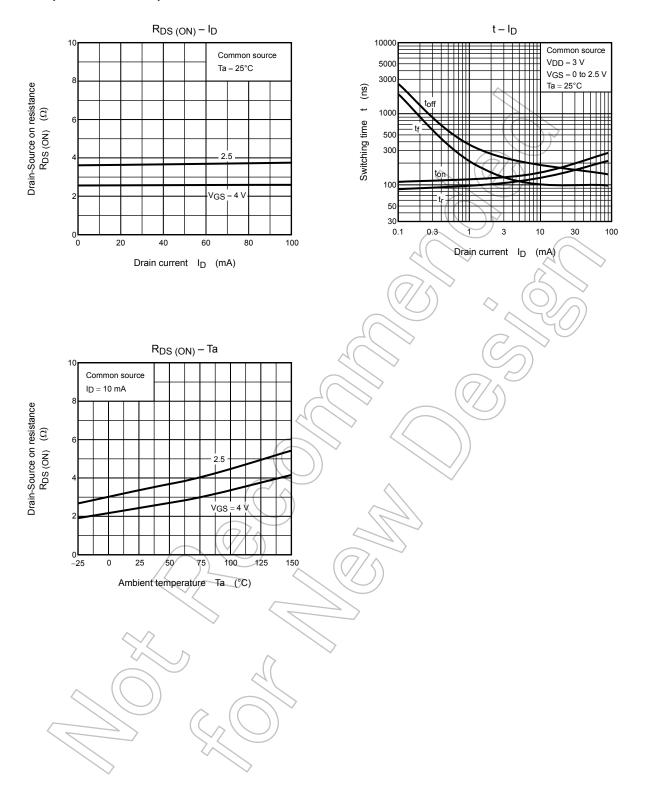








## Q2 (Nch MOSFET)



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